

2SK2788

Silicon N Channel MOS FET High Speed Power Switching

REJ03G1033-0200

(Previous: ADE-208-538)

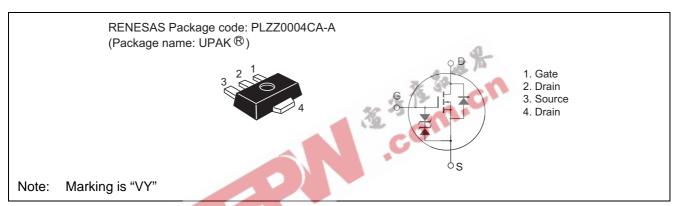
Rev.2.00

Sep.07,2005

Features

- Low on-resistance $R_{DS(on)} = 0.12~\Omega~typ~(V_{GS} = 10~V,~I_D = 1~A) \label{eq:DS(on)}$
- Low drive current
- High speed switching
- 4 V gate drive devices.

Outline



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Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	60	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I _D	2	Α
Drain peak current	I _{D(pulse)} *1	4	Α
Body to drain diode reverse drain current	I _{DR}	2	Α
Channel dissipation	Pch*2	1	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. When using the alumina ceramic board (12.5 x 20 x 0.7 mm)

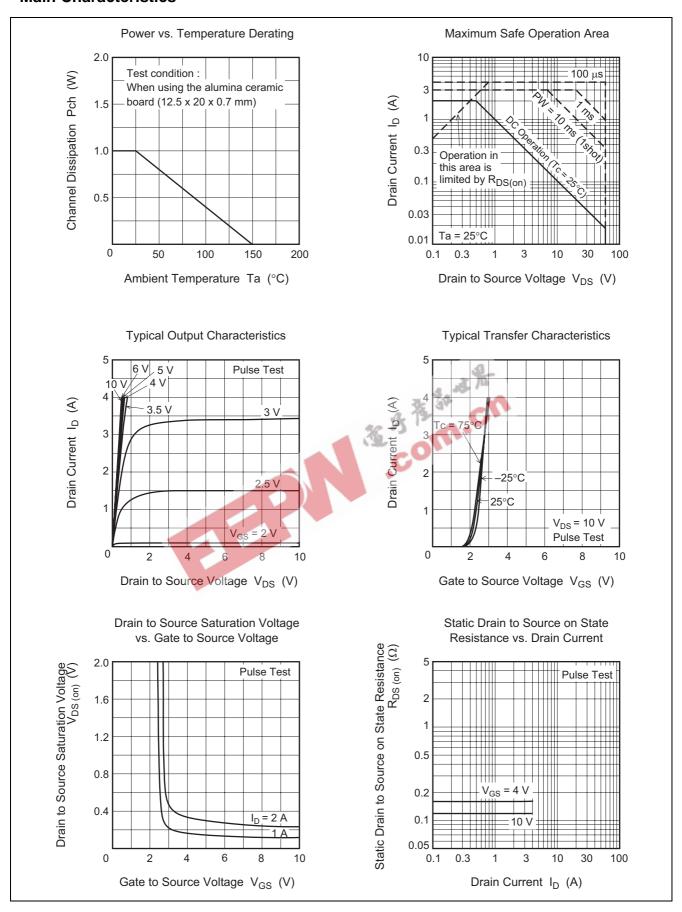
Electrical Characteristics

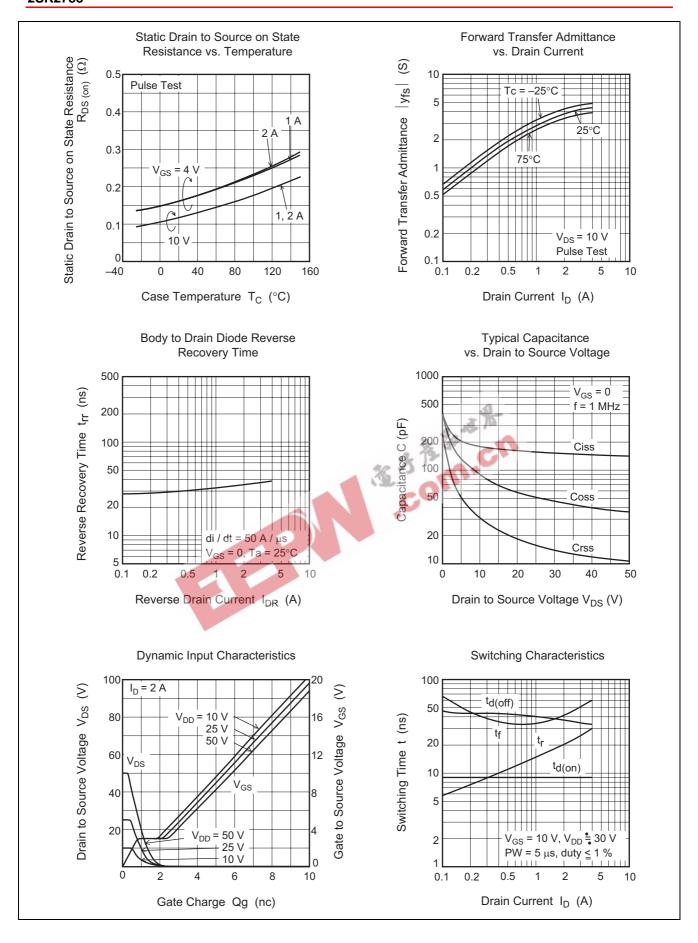
 $(Ta = 25^{\circ}C)$

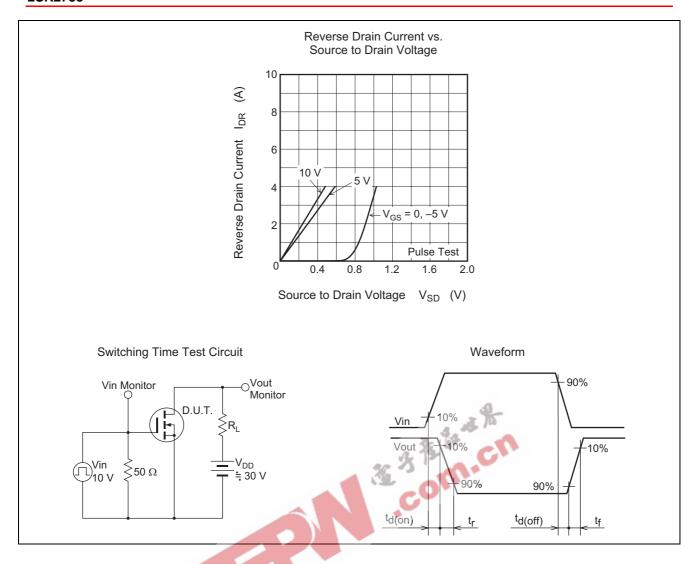
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	60	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	10	μΑ	$V_{DS} = 60 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.0	_	2.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state	R _{DS(on)}	_	0.12	0.16		$I_D = 1 \text{ A}, V_{GS} = 10 \text{ V}^{*3}$
resistance	R _{DS(on)}	_	0.16	0.25	Ω	$I_D = 1 \text{ A}, V_{GS} = 4 \text{ V}^{*3}$
Forward transfer admittance	y _{fs}	1.6	2 .8	<u>_</u>	S	$I_D = 1 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$
Input capacitance	Ciss	T	180	0	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	4	90		рF	f = 1 MHz
Reverse transfer capacitance	Crss	7	30	_	pF	
Turn-on delay time	t _{d(on)}		9	_	ns	$V_{GS} = 10 \text{ V}, I_D = 1 \text{ A},$
Rise time	tr	_	15	_	ns	$R_L = 30 \Omega$
Turn-off delay time	t _{d(off)}	_	40	_	ns	
Fall time	t _f	_	35	_	ns	
Body to drain diode forward voltage	V _{DF}	_	0.9	_	V	$I_D = 2 A, V_{GS} = 0$
Body to drain diode reverse	t _{rr}	_	35	_	ns	$I_F = 2 \text{ A}, V_{GS} = 0$
recovery time						$di_F/dt = 50A/\mu s$

Notes: 3. Pulse test

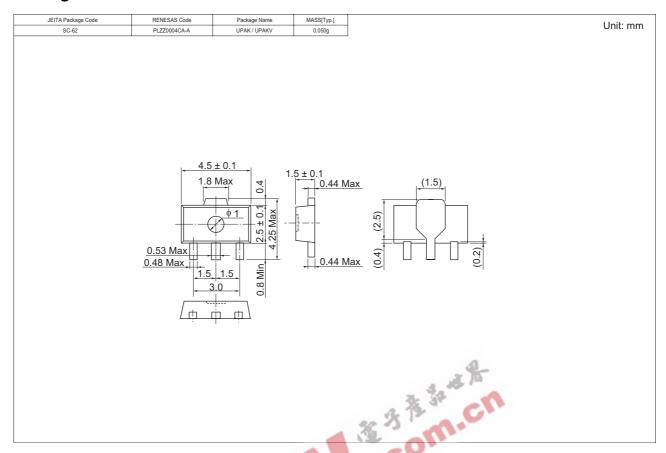
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SK2788VYTL-E	1000 pcs	Taping
2SK2788VYTR-E	1000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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